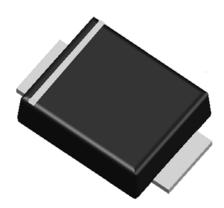




Surface Mount General Purpose Rectifier





Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- \bullet Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

Typical Applications

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer and telecommunication.

Mechanical Data

• Package: SMBF

Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free

• Terminals: Tin plated leads, solderable per

J-STD-002 and JESD22-B102

• Polarity: Cathode line denotes the cathode end

■Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	GS2ABF	GS2BBF	GS2DBF	GS2GBF	GS2JBF	GS2KBF	GS2MBF
Device marking code			GS2ABF	GS2BBF	GS2DBF	GS2GBF	GS2JBF	GS2KBF	GS2MBF
Maximum Repetitive peak reverse voltage	V_{RRM}	V	50	100	200	400	600	800	1000
Maximum RMS Voltage	V _{RMS}	V	35	70	140	280	420	560	700
Maximum DC Blocking Voltage	V _{DC}	V	50	100	200	400	600	800	1000
Average rectified output current @60Hz sine wave, resistance load, TL (Fig.1)	lO	Α	2.0						
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave,1 cycle, Tj=25°C		А	50						
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25°C	I _{FSM}		100						
Current squared time @1ms≤t≤8.3ms Tj=25°C,Rating of per diode	l²t	A ² s	10.735						
Typical junction capacitance @Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	Cj	pF	12						
Storage temperature	T _{stg}	°	-55 ~ + 150						
Junction temperature	Tj	°C	-55 ~ + 150						

■Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	GS2ABF	GS2BBF	GS2DBF	GS2GBF	GS2JBF	GS2KBF	GS2MBF
Maximum instantaneous forward voltage drop per diode	VF	V	IFM=2.0A				1.1			
Maximum DC reverse current at rated DC blocking voltage per	lR		T _j =25°C	5.0						
diode	אי	μΑ	T _j =125°C	100						

■Thermal Characteristics (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	GS2ABF	GS2BBF	GS2DBF	GS2GBF	GS2JBF	GS2KBF	GS2MBF	
	R ₀ J-A ⁽¹⁾					60				
Typical Thermal Resistance	R ₀ J-L ⁽¹⁾	°C/W	20							
	RθJ-C ⁽¹⁾		15							

Note:

■ Characteristics (Typical)

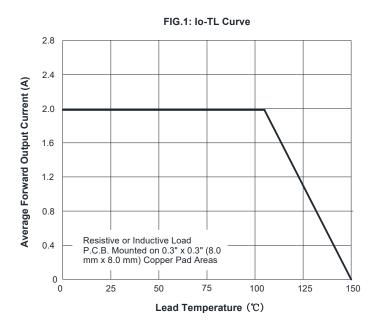
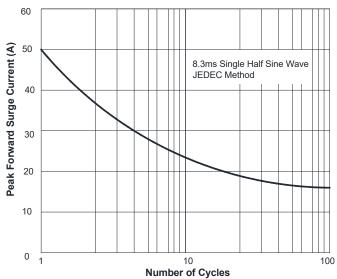
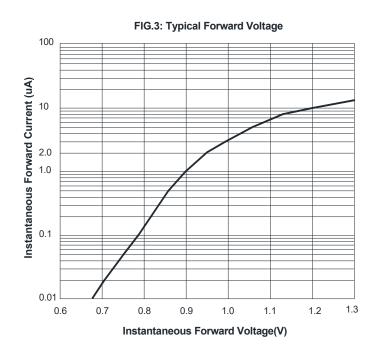
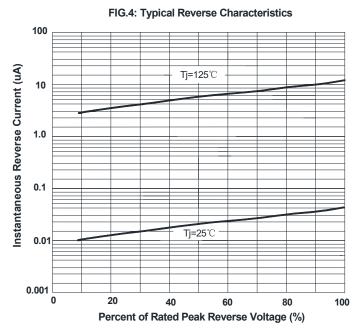


FIG.2: Forward Surge Current Capability



⁽¹⁾ Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3" x 0.3" (8.0 mm x 8.0 mm) copper pad areas

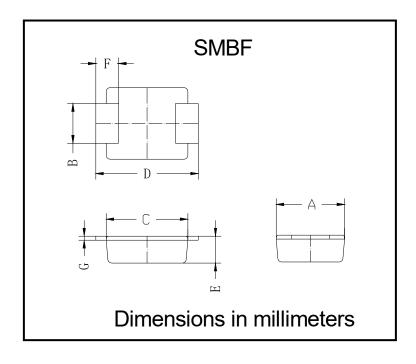




■Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
GS2ABF - GS2MBF	F1	Approximate 0.065	5000	1	80000	13" reel

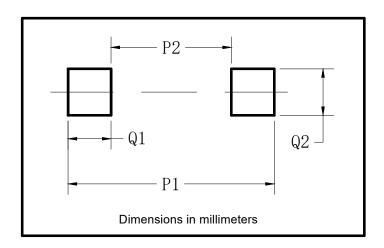
■ Outline Dimensions



SMBF					
Dim	Min	Max			
Α	3.40	3.80			
В	1.90	2.10			
С	4.15	4.45			
D	5.10	5.60			
Е	1.05	1.55			
F	0.70	1.35			
G	0.15	0.25			



■ Suggested pad layout



Dim	Milimeters
P1	6.20
P2	2.40
Q1	1.90
Q2	2.20



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